



DESCRIPTION:

The products are thyristor opto-couplers in LSOP5 and LSOP5W packages. The device combines an AlGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon random-phase photo triac, the device provides the most stable isolation feature. The products are widely used in solenoid/valve controls, lighting controls, motor controls, temperature controls, static AC power switches, solid state relays, interfacing microprocessors up to 265 V_{AC} peripherals.

MAIN FEATURES

High isolation 5000 VRMS

DC input with random-phase photo triac output

Operating temperature range -55 to 110

REACH & RoHS compliance

HBM: H3A; MM: M4; CDM: C3

CQC approved

VDE approved

UL approved



ABSOLUTE MAXIMUM RATINGS (Temperature=25°C)

Parameter		Symbol		Value	Unit
Input	Forward Current	I_F		50	mA
	Peak Forward Current	I_{FP}		1	A
	Reverse Voltage	V_R		6	V
	Power Dissipation	P_D		75	mW
Output	Off-state Output Terminal Voltage	V_{OFF}	JOCSR21X	600	V
			JOCSR31X	800	
	Peak On-state Current (100μs pulse, 120 pps)	I_{TP}		2	A
	On-state RMS Current	$I_{T(RMS)}$		100	mA
	Peak Repetitive Surge Current ($P_W=10$ ms)	I_{TSM}		1.2	A
	Output Power Dissipation	P_O		250	mW
Total Power Dissipation		P_{tot}		325	mW
Isolation Voltage		V_{iso}		5000	Vrms



Operating Temperature	T_{opr}	-55~110	
Junction Temperature	T_j	125	
Storage Temperature	T_{stg}	-55~125	
Soldering Temperature	T_{sol}	260	
Peak pulse voltage ($T_j=25$; non-repetitive,off-state)	V_{pp}	1	kV

ORDERING INFORMATION

J	OC	S	R	2	1	A	-L5X	/
JieJie Microelectronics Co., Ltd.	Opto Coupler	SCR	Random phase					None:T1 R:T2
						A:I _{FT} 10mA B:I _{FT} 5mA C:I _{FT} 3mA		None:LSOP5 W:LSOP5W
						I _{T(RMS)} :100mA		
						2:V _{OFF} 600V 3:V _{OFF} 800V		

Packing Quantity			
Option	Quantity	Quantity – Inner box	Quantity –Outer box
LSOP5	3000 Units/Reel	2 Reels/Inner box	5 Inner box/Outer box =30k Units

MARKING



Characteristics Curves

FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

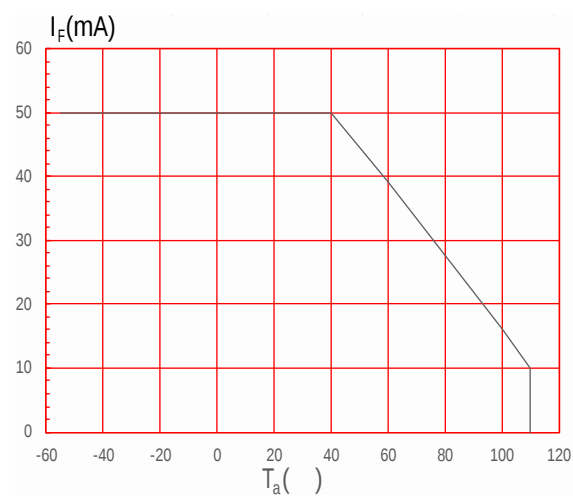


FIG.3:

FIG.2: On-state Terminal Current vs. Ambient Temperature

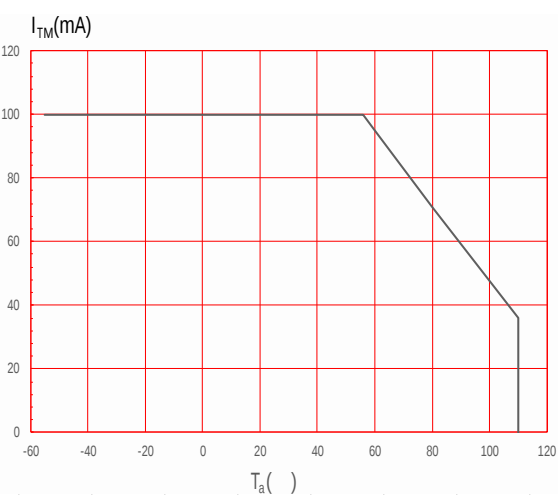


FIG.7: Normalized On-state Terminal Voltage vs. Ambient Temperature

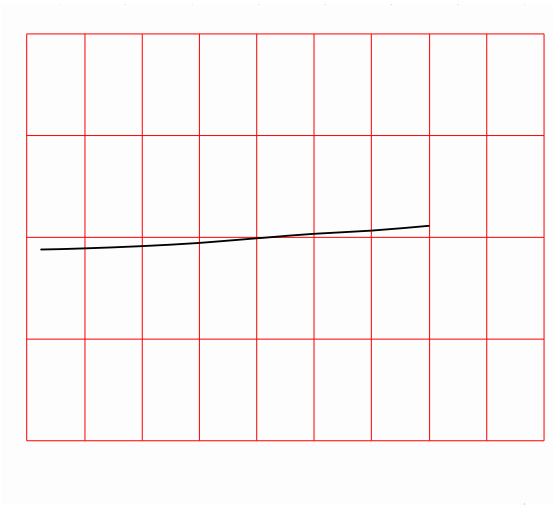


FIG.8: On-state Terminal Voltage vs. On-state Terminal Current

TEST CIRCUITS

FIG.12: Test Circuits of Turn On Time

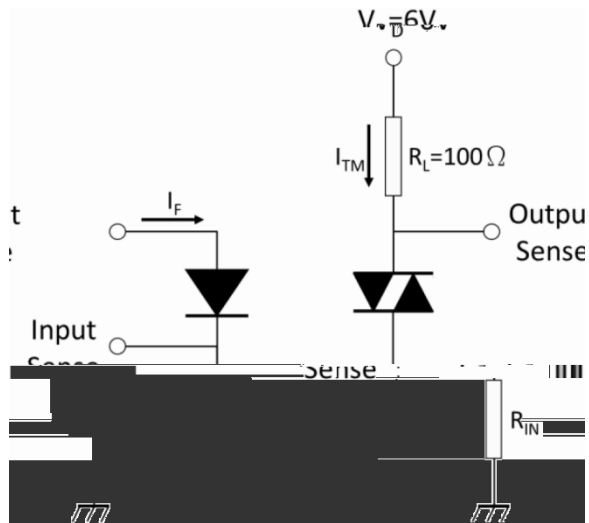


FIG.13: Waveforms of Turn On Time

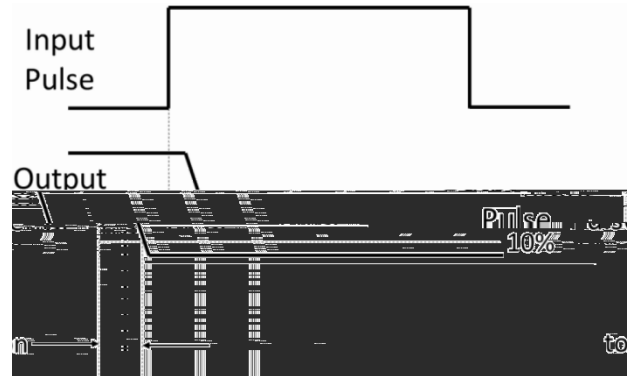


Fig.14: Test Circuits of dV/dt

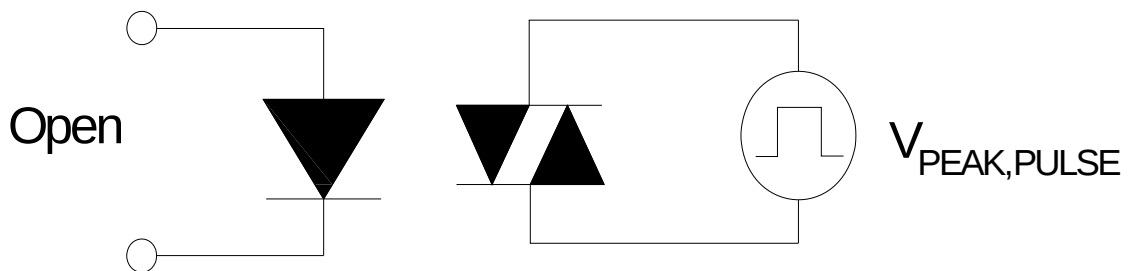


Fig.15: Waveforms of dV/dt

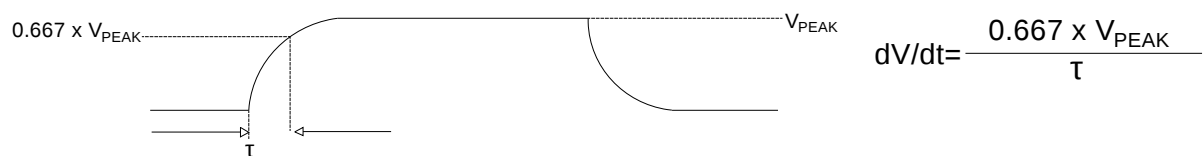
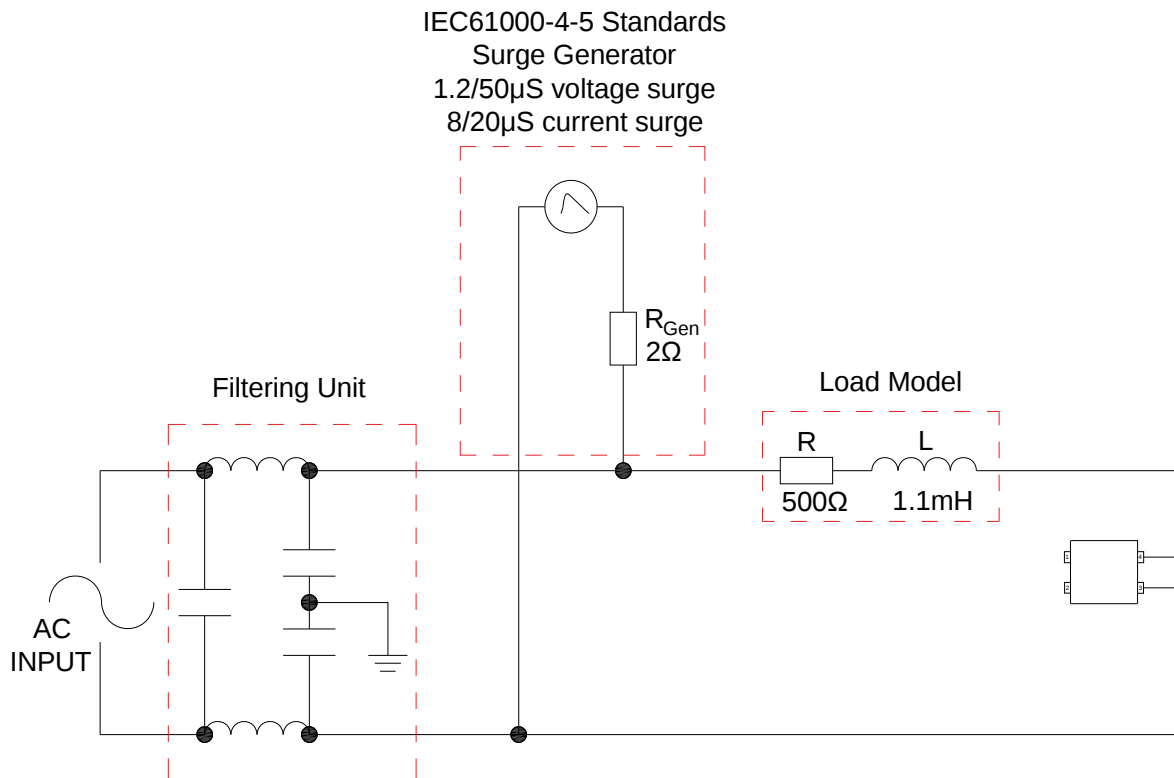
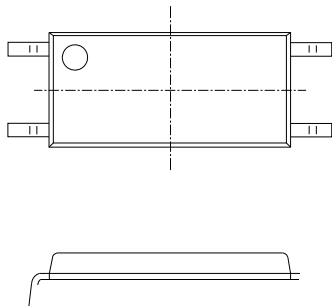


FIG.16: Test circuit for inductive and resistive loads to IEC-61000-4-5 standards



Package Dimension (Unit: mm)

LSOP5



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	7.40		7.80	0.291		0.307
B	3.40		3.80	0.134		0.150
C	0.00		0.20	0.000		0.008
D	1.80		2.20	0.071		0.087
E	8.10		8.70	0.319		0.343
F	0.40		1.00	0.016		0.039
G	9.90		10.50	0.390		0.413
H	0.10		0.30	0.004		0.012
I	1.80		2.40	0.071		0.094
J	0.25		0.55	0.010		0.022
K						

RECOMMENDED SOLDER MASK (Dimensions in mm unless otherwise stated)

LSOP5

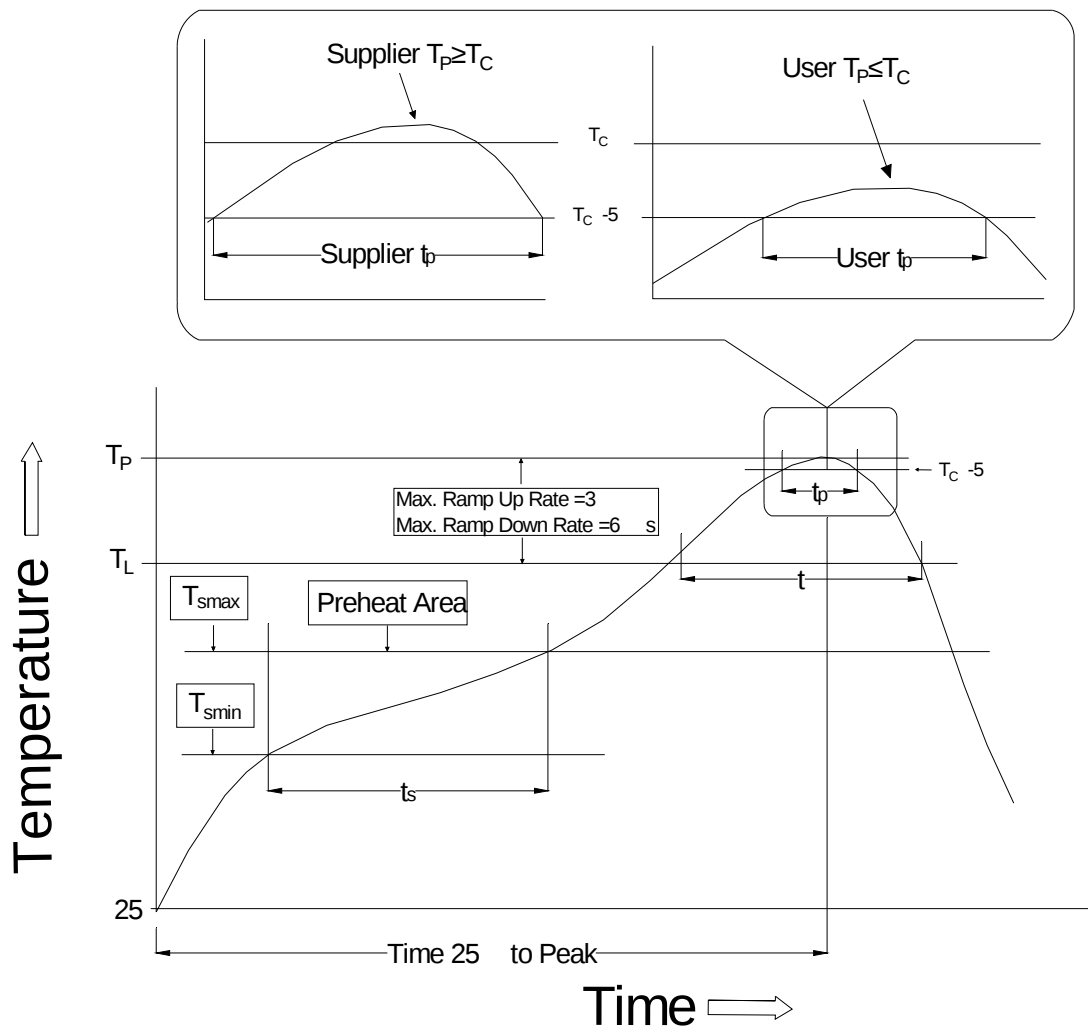


CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option None

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
D0			1.60 "			
P0	3.90					
P1						
E	1.65					
T						

REFLOW INFORMATION



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T_{smin})	100	150
Temperature Max. (T_{smax})	150	200
Time (t_s) from (T_{smin} to T_{smax})	60-120 seconds	60-120 seconds
Ramp-up Rate (t_L to t_P)	3 °C/second max.	3 °C/second max.
Liquidus Temperature (T_L)	183	217
Time (t_L) Maintained Above (T_L)	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235 +0 /-5	260 +0 /-5
Time (t_P) within 5 °C of 260	10 seconds	10 seconds
Ramp-down Rate (T_P to T_L)	3-6 °C/second	3-6 °C/second
Time 25 °C to Peak Temperature	6 minutes max.	8 minutes max.

Note:

1. Reflow soldering is recommended at the temperatures and times shown, no more than three times.
2. Avoid direct contact between the epoxy body and any tools or surfaces exceeding its maximum storage temperature.
3. Application of pressure on the epoxy body is prohibited at elevated temperatures. In specific scenarios, any applied force must not exceed 2.5N.
4. Ensure the component has cooled to ambient temperature before proceeding with any subsequent manufacturing steps.
5. The component has a shelf life of one year when stored under standard conditions.
6. Recommend storage Temp.: 0~40°C;
Recommend storage humidity: <60%;
MSL level: MSL 1

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